ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® MOUSTRIES® International and Pa	PC. Bannockl	burn, Illinois, A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration entities the declaration entities and the declaration entities and the declaration entities and the declaration entities are an entities are an entities and the declaration entities are an entits are an entities are an entits are an entities are an entities	on of the su	bstances v all lower	vithin the manufactu level materials for v	rer listed which the r	tem. Note: nanufacture	if the item is an as er has engineering	sembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form   http://www.ipc.org/IPC-175x Distri				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg					lfg Informa	ation			
upplier Information														
Company name* Company u			y unique ID			Unique ID Authority				Respon	Response Date*			
isemi								2025-06-02						
Contact Name	ct Name Title - Contact					Phone - Contact*				Email -	Email - Contact*			
roduct-Env-Stewards Product Envir			viro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative			esentative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product E			act Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	Version Manufacturing Site			Weight*	UOM	Unit Type	
	MMBF1	MBF170 FET 60V 5.0 m		Jhm SOT23		2025-06-02		C	CNF		8.02	mg	Each	
Ianufacturing Proccess Informa	tion													
Terminal Plating / Grid Array M	aterial	Terminal Base Alloy		J-STD-020 MSI	SL Rating Peak		A Process Body Temperature Max Time at Pea		k Tempera	ture Num	ber of Reflow Cyc	les		
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30	seco	nds 3			
omments														
vel 1 - maximum time at peak temperat	ure during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.05	mg	Supplier	Silicon (Si)	7440-21-3		0.05	mg
Lead Frame	2.92	mg	Supplier	Silver (Ag)	7440-22-4		0.0584	mg
			В	Nickel (Ni)	7440-02-0		1.06	mg
			Supplier	Iron (Fe)	7439-89-6		1.4658	mg
			Supplier	Copper (Cu)	7440-50-8		0.3358	mg
Mold Compound-Black	4.9	mg		Epoxy resin	proprietary data		0.245	mg
			Supplier	Phenolic Resin	Proprietary Data		0.245	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.098	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0245	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.2875	mg
Plating	0.14	mg	Supplier	Tin (Sn)	7440-31-5		0.14	mg
Wire Bond - Cu	0.01	mg	Supplier	Copper (Cu)	7440-50-8		0.01	mg